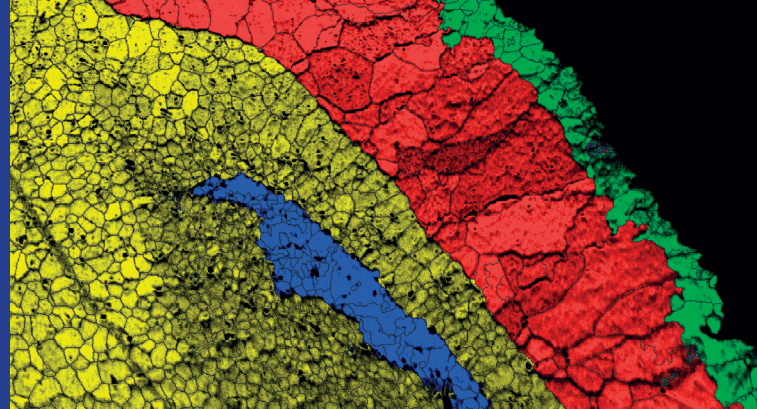


INTERNATIONAL WORKSHOP ON FAILURE ANALYSIS AND MATERIAL CHARACTERIZATION



WORKSHOP SCHEDULE

■ Thursday, 8th March

- 11:30 Introduction to Fraunhofer Center for Applied Microstructure Diagnostics,
Matthias Petzold, Fraunhofer Institute for Mechanics of Materials IWM
- 11:45 Advanced Failure Analysis: A Must for Today's Package Developments
Klaus Pressel, Infineon Technologies AG
- 12:20 Failure Analysis on embedded Wafer Level Ball Grid Arrays (eWLB)
Walter Mack, Infineon Technologies AG
- 12:45 Reliability of Micro Systems using open TSV Interconnects
Franz Schrank, austriamicrosystems AG
- 13:10 Requirements on MEMS Wafer Bonding and Reliability
Holger Rank, Robert Bosch GmbH
- 13:35 Lunch
- 14:35 Application of Lock in-Thermography for advanced microelectronic Devices
Rudolf Schlangen, DCG Systems, Inc.
- 15:00 Developments in Scanning Acoustic Microscopy for Defect Analysis
Peter Czurratis, PVA Tepla Analytical Systems AG
- 15:25 Non-destructive X-ray Inspection for 3D Integration
Raimund Sauter, L.O.T.-Oriel GmbH & Co. KG
- 15:50 A new combined Laser/FIB Tool for Target Preparation in packaged Devices
Roland Salzer, Zeiss NTS GmbH
- 16:15 Coffee Break

- 16:35 High throughput Cross Sectioning using Plasma-FIB Milling and Laser Ablation
Laurens Kwakmann, FEI Company
- 17:00 Laser Micromachining with Ultra Short Pulse Lasers
Tino Petsch, 3D-Micromac AG
- 17:25 AlCu Grain Size Investigations for High Performance Subhalfmicron Automotive Applications
Reinhard Portius, X-FAB Semiconductor Foundries AG
- 17:50 Advanced Methods for IC Failure Analysis
Frank Altmann, Fraunhofer Institute for Mechanics of Materials IWM
- 18:15 Ultra-high 2D and 3D Imaging SIMS with Cluster Ions – approaching the Physical Limits
Sven Kayser, Ion-ToF GmbH
- 19:15 Bus Transfer
- 20:00 Dinner at »Bergschenke«

■ Friday, 9th March

- 9:00 Automotive Electronics – Trends and Challenges
Wolfgang Wondrack, Daimler AG
- 9:35 Reliability of Wire Bonded Contacts with Overplated Pad Metallization
Sieglinde Kraus, Continental Automotive GmbH
- 10:00 On the Intermetallic Corrosion of Cu-Al Wire Bonds
Tim Böttcher, NXP Semiconductors
- 10:25 Development of new Bonding Wire Materials
Eugen Milke, Heraeus GmbH
- 10:50 New Method for Decapsulation of Copper Wire Devices using Laser and sub-ambient Temperature Chemical Etch
Matthew Lefevre, Digit Concept

- 11:15 Coffee Break
- 11:30 Characteristic Life Time Optimization of Al Heavy Wire Bond Contacts
Stephan Röß, Conti Temic microelectronic GmbH
- 11:55 Requirements and Challenges in Ag Sintering Technologies for Power Electronics
Mathias Kock, Danfoss Silicon Power GmbH
- 12:20 Properties of DAB Substrates for Power Electronics Modules
Heiko Knoll, IXYS Semiconductor GmbH
- 12:45 Mechanical Testing for Quality Surveillance of Power Electronics Components
Dirk Schade, XYZTec Germany
- 13:10 Lunch
- 14:10 Fracture Strength of LED Chips
Ingo Neudecker, OSRAM Opto Semiconductors GmbH
- 14:35 Mechanical Modelling of Electronic Packaging and Interconnection Materials
Torsten Hauck, Freescale Halbleiter Deutschland GmbH
- 15:00 Strength and Life Time Properties of Micronozzles applied in Medical Devices
Klaus Kadel, Boehringer Ingelheim microParts GmbH
- 15:25 Colours and Pigments: the Use of Microscopy to understand the Appearance of Effect Coatings
Dr. Adalbert Huber, Merck KGaA
- 15:50 Wrap up
Matthias Petzold, Fraunhofer Institute for Mechanics of Materials IWM
- 16:00 Coffee Break
- 16:15 Lab/Tool Demos
- 18:00 End of Workshop